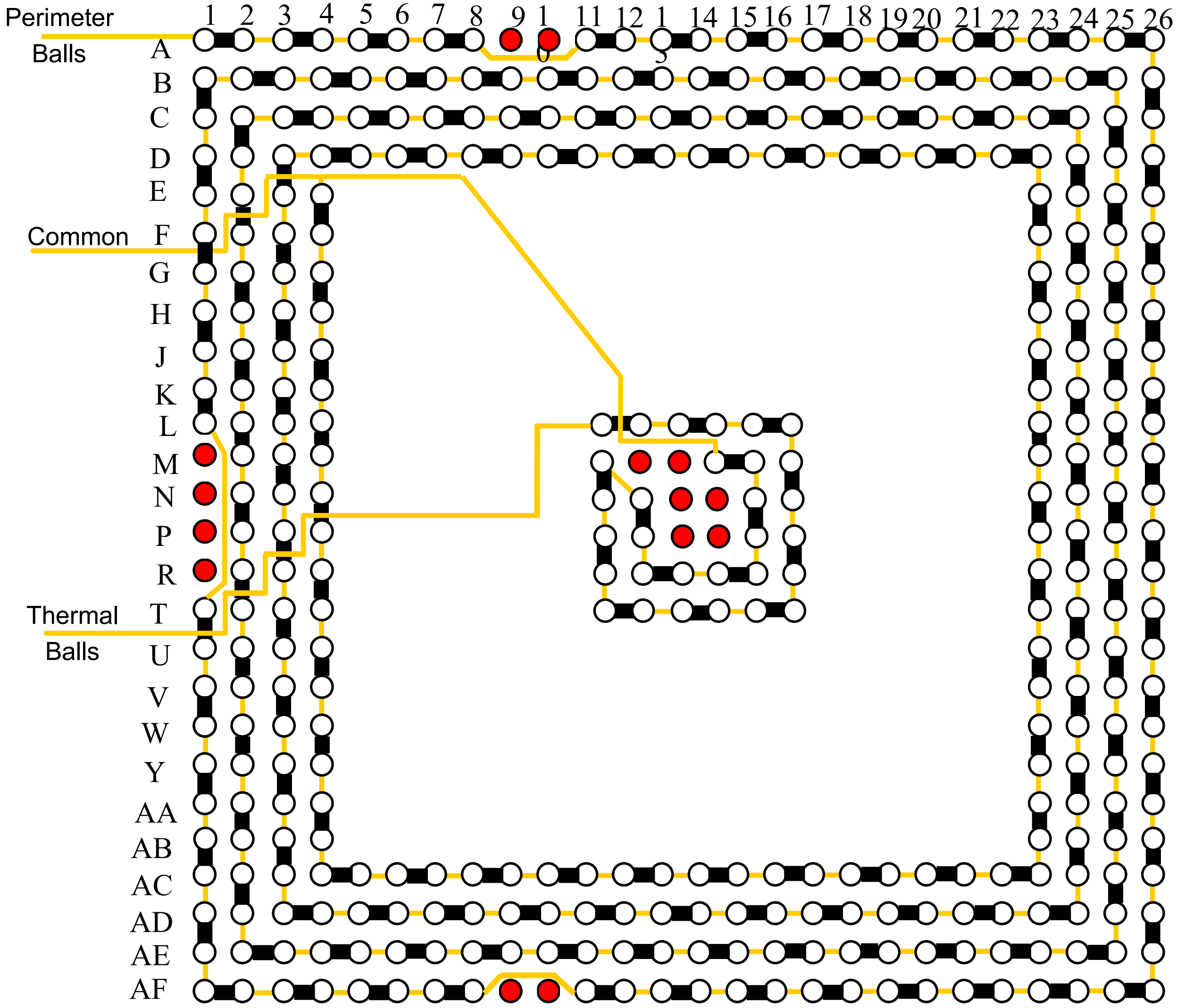
Pin PBGA Daisy Chain Package and Suggested Test Board



Looking *through*
Package or
at Test Board

* 1.0 mm Pitch
* 26x26 Array (4 Row Perim)
* 36 Thermal Balls
* 27x27 mm Body Size
* 0.5 mm Package Pad
* 0.6 mm Solder Ball Diam.

— = Suggested Test Board Trace
▬ = BGA Package Trace

● = Do not connect.
Freescale Internal
Use Only.